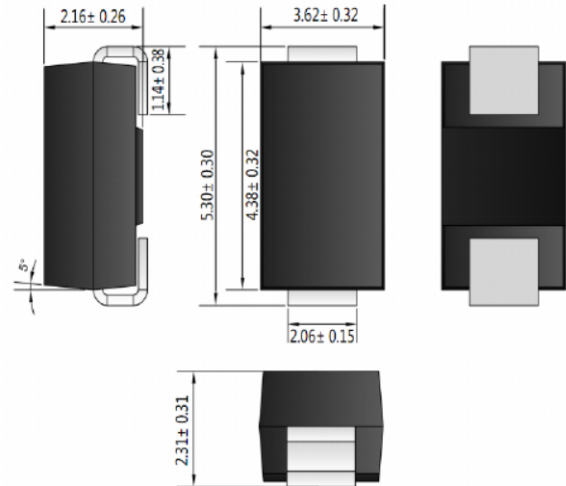


2.0A SURFACE MOUNT GLASS PASSIVATED SUPERFAST DIODE
Features

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Surge Overload Rating to 60A Peak
- Low Power Loss
- Built-in Strain Relief
- Plastic Case Material has UL Flammability Classification Rating 94V-0

Mechanical Data

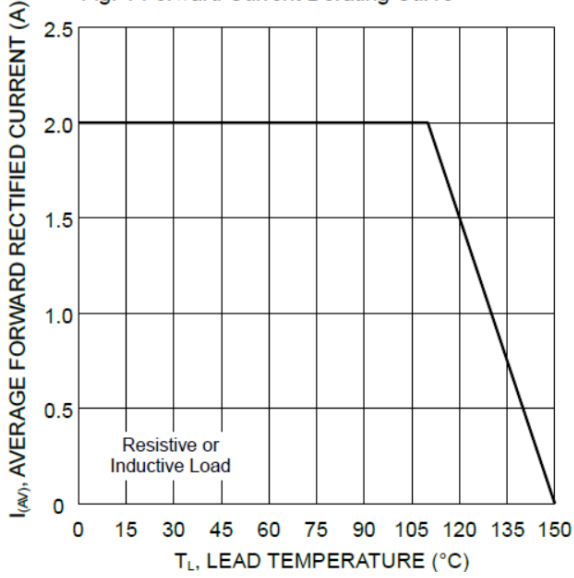
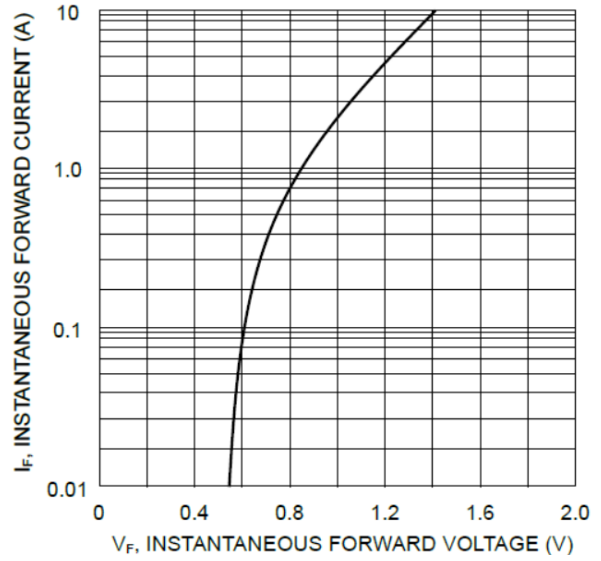
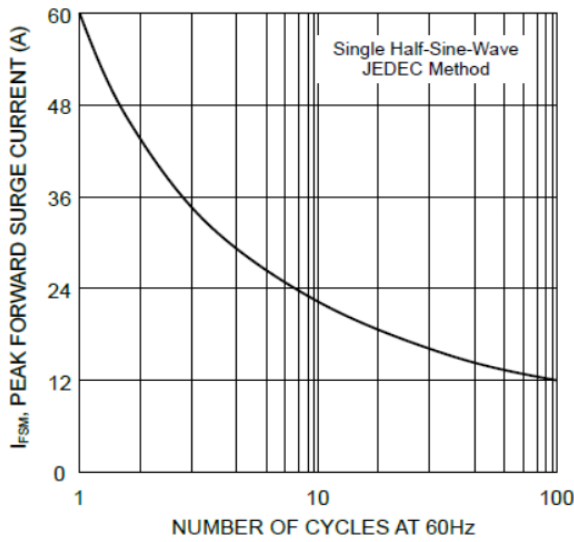
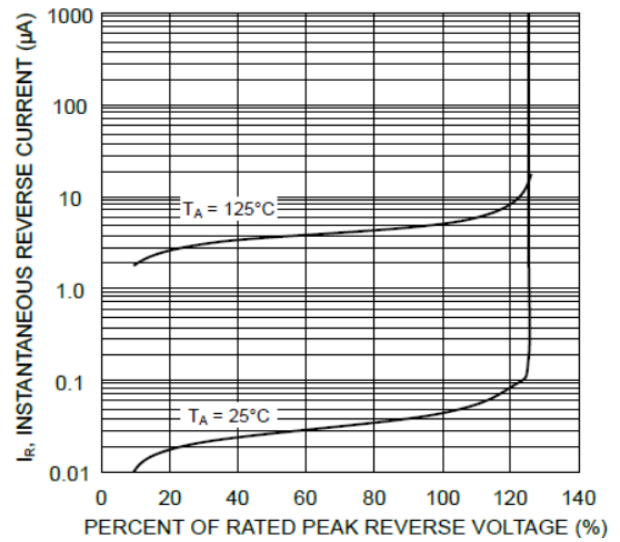
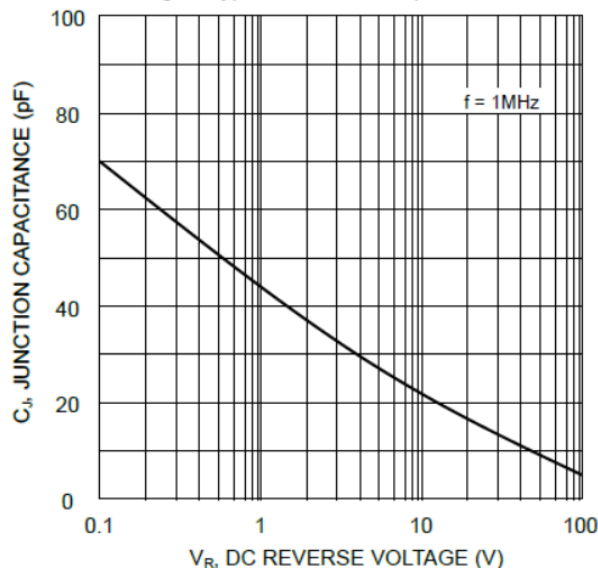
- Case: SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)
- **Lead Free: For RoHS / Lead Free Version**

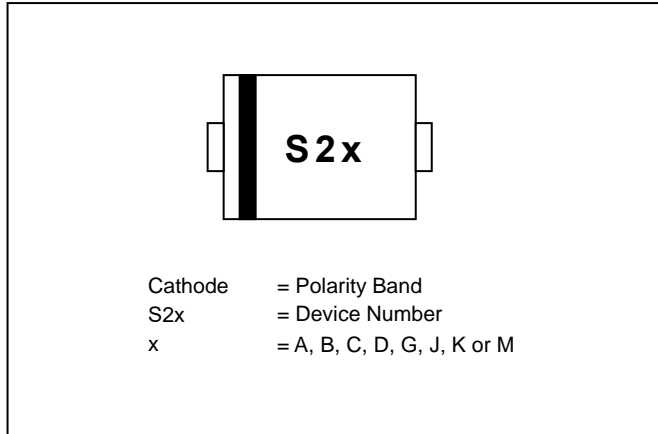
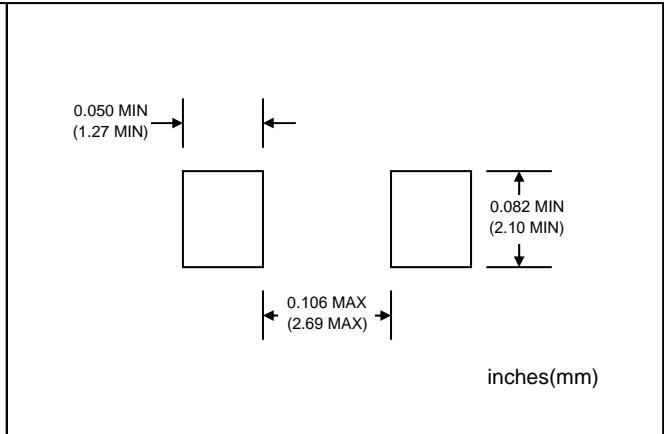
SMB /DO-214AA

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

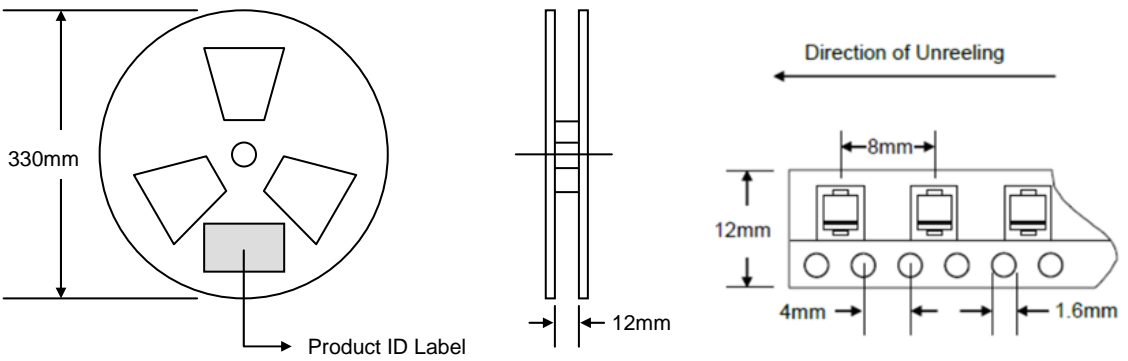
Characteristic	Symbol	S2A	S2B	S2D	S2G	S2J	S2K	S2M	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V_{RWM}								
DC Blocking Voltage	V_R								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_L = 110^\circ\text{C}$	I_o	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	60							A
Forward Voltage @ $I_F = 2.0\text{A}$	V_{FM}	1.1							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I_{RM}	5.0 200							μA
Typical Junction Capacitance (Note 1)	C_J	30							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	53							$^\circ\text{C}/\text{W}$
Typical Thermal Resistance (Note 3)	$R_{\theta JL}$	16							
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150							$^\circ\text{C}$

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.
 2. Junction to ambient, device mounted on PCB with 8.0mm x 8.0mm copper pads.
 3. Junction to lead, device mounted on PCB with 8.0mm x 8.0mm copper pads.

Fig. 1 Forward Current Derating Curve

Fig. 2 Typical Forward Characteristics

Fig. 3 Forward Surge Current Derating Curve

Fig. 4 Typical Reverse Characteristics

Fig. 5 Typical Junction Capacitance


MARKING INFORMATION

RECOMMENDED FOOTPRINT

PACKAGING INFORMATION

TAPE & REEL



Reel Diameter (mm)	Quantity (PCS)	Inner Box Size L x W x H (mm)	Quantity (PCS)	Carton Size L x W x H (mm)	Quantity (PCS)	Approx. Gross Weight (KG)
330	3,000	340 x 337 x 45	6,000	370 x 370 x 420	48,000	14.0

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